

## SUA-110E5-30xx-S277

鍍層厚度：

|             |
|-------------|
| Blank : 1u" |
| 2 : 15u"    |
| 3 : 30u"    |

HOUSING：

|                  |
|------------------|
| Blank : LCP,Blue |
| K : LCP,BLack    |
| GR : PBT,Green   |

### NOTE:

#### 1.MATERIAL:

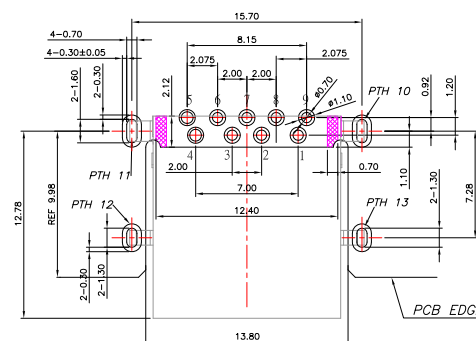
- 1.1 Housing: Plastic,(UL94V-0)
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

#### 2.Finish:

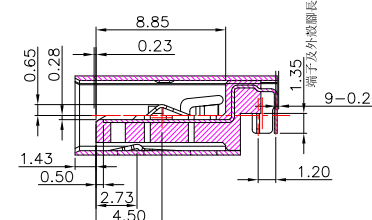
- 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

#### 3.SPECIFICATION:

- 3.1 Rate: 30V DC , 1.5 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N

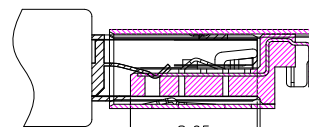


### RECOMMENDED PCB LAYOUT

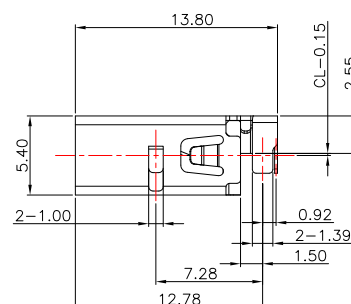


SECTION A-A

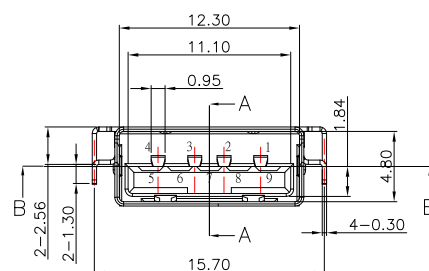
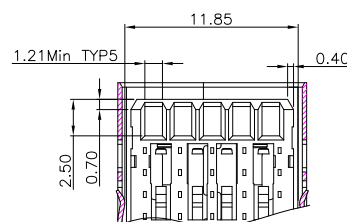
| Pin # | SIGNAL NAME | DESCRIPTION                              | MATING SEQUENCE |
|-------|-------------|------------------------------------------|-----------------|
| 1     | VBUS        | POWER                                    | SECOND          |
| 2     | D-          | USB 2.0 DIFFERENTIAL PAIR                | THIRD           |
| 3     | D+          |                                          |                 |
| 4     | GND         | GROUND FOR POWER RETURN                  | SECOND          |
| 5     | StdA_SSRX-  | SUPERSPEED RECEIVER DIFFERENTIAL PAIR    | LAST            |
| 6     | StdA_SSRX+  |                                          |                 |
| 7     | GND_DRAIN   | GROUND FOR SIGNAL RETURN                 |                 |
| 8     | StdA_SSTX-  | SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR |                 |
| 9     | StdA_SSTX+  |                                          |                 |
| Shell | Shield      | CONNECTOR METAL SHELL                    | FRIST           |



CONNECTOR MATEING



SECTION B-B



(BOTTOM VIEW)



建倚科技股份有限公司  
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TOLERANCE UNLESS  
OTHERWISE STATED :

Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3°

3RD.  
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu  
CHECKED BY: Jacky Chen  
APPROVED BY: Tony Kao

DATE: 08/19/20  
DATE: 08/19/20  
DATE: 08/19/20

MAT'L  
FINISH  
SCALE  
SHEET NO.

TITLE  
MODLE  
DWG NO.  
PART NO.

CONNECTOR  
USB A/F 3.0 DIP 沉板, 板上H:2.56mm,  
無捲邊反向

SUA-110E5-30xx-S277

SIZE  
A4  
VER  
R4

| ITEM NO | DESCRIPTION      | DRAWN | DATE   |
|---------|------------------|-------|--------|
| 4       | 新增尺寸標註           | Jack  | 081920 |
| 3       | 新增PCB LAYOUT尺寸標註 | Lan   | 041819 |
| 2       | 新增顏色及材質選項        | Jack  | 042817 |
| 1       | 更新PCB LAYOUT尺寸   | Jack  | 012017 |